

# All-in-glass packaging for VCSELs and other optical systems in harsh environments

EPIC Meeting on New Space at European Space Agency, September 2019  
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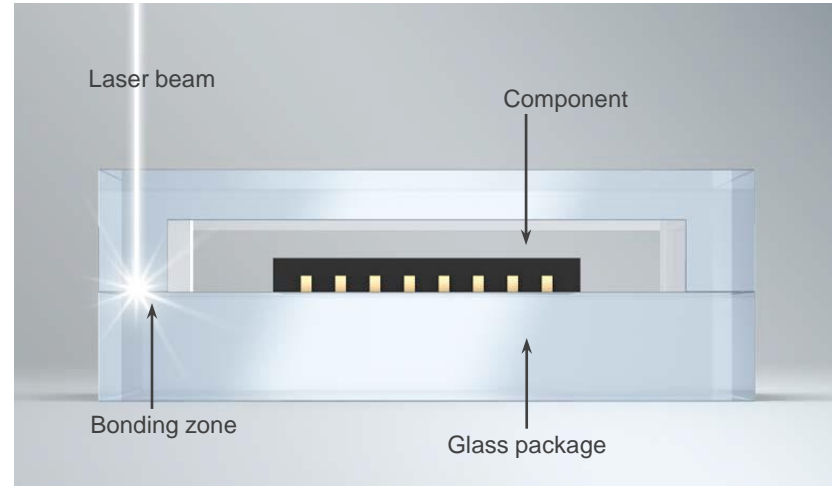
# SCHOTT Primoceler Oy: Who are we?

- Glass Micro Bonding specialist founded in 2010 and headquartered in Tampere, Finland
- Joined SCHOTT AG in August 2018
- Pioneering technology: Unique additive-free, room temperature hermetic glass bonding
- Specialized in medical implants, microfluidics, micro-electronics and micro-optics



# What is Glass Micro Bonding?

- **Laser-based** hermetic bonding: extremely precise sealing
- **Contactless** method: material surfaces are untouched
- **Minimal heat load**: laser-precision enables a heat-affected zone of just a few micrometers
- **One-step** manufacturing process



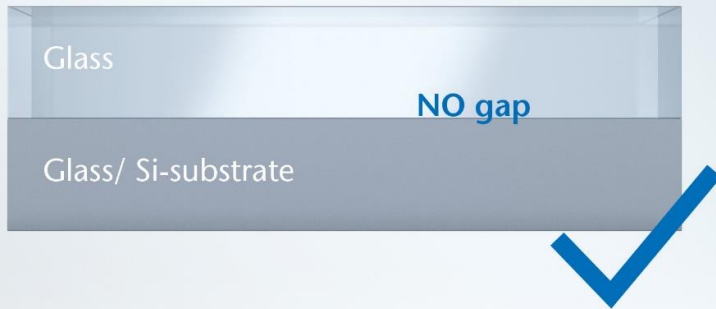
# Up to the Challenge: SCHOTT Primoceler™ Glass Micro Bonding is a Proven Superior Alternative to Existing Sealing Methods

	<b>SCHOTT Primoceler™</b>	Anodic bonding	Direct / fusion bonding	Glass frit	Epoxy (UV)	Epoxy (thermal)
<b>Hermetic</b>	Yes	Yes	Yes	No / In rare circumstances	No	No
<b>Sealing Process</b>	No additives	Silicon or metal needed Glass-glass not possible	No additives	Additives needed	Additives needed	Additives needed
<b>Process temperature</b>	Room temperature	440 °C (824 °F)	1000 °C (1832 °F) (no plasma) 440 °C (824 °F) (with plasma)	440 °C (824 °F)	Room temperature	200 °C (392 °F)
<b>Clean room class requirement</b>	100 / 1000	100	10	1000	1000	1000
<b>Surface quality required (Ra)</b>	< 10 nm	< 2 nm	< 0.5 nm (no plasma) < 2 nm (with plasma)	< 1 um	< 1 um	< 1 um

# Gap Control and Additive-Free Technology Enables Higher Reliability for Micro-Optic Applications

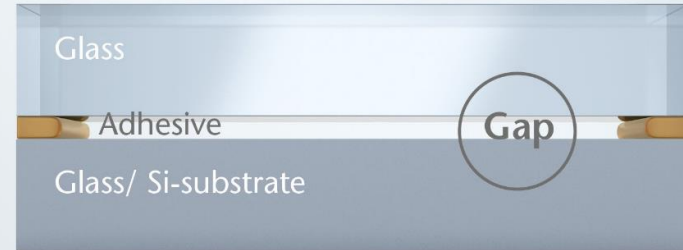
## SCHOTT Primoceler Glass Micro Bonding

- ✓ Direct bonding without additive materials
- ✓ No gap between top and bottom substrates



## Other Bonding Methods

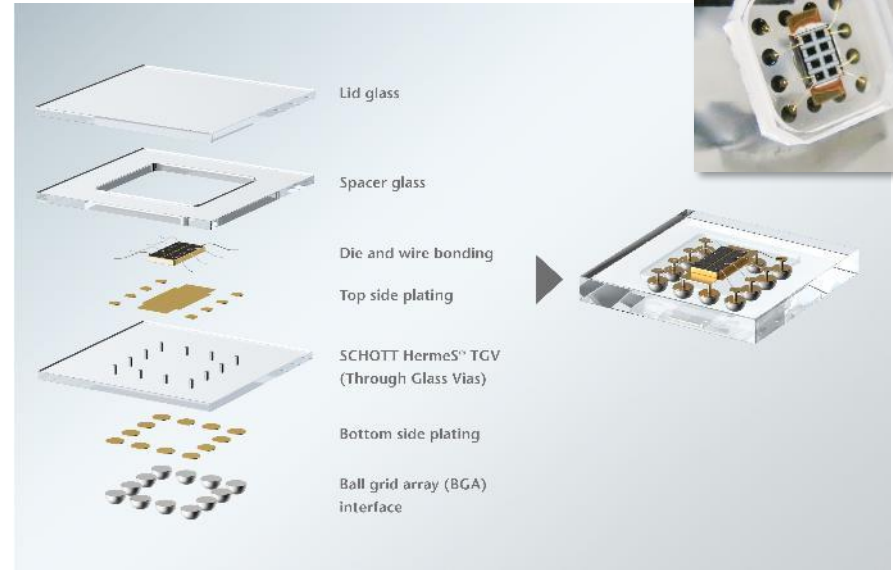
- Additive materials used for bonding
- Gap between top and bottom substrates
- Controlling the gap is difficult or impossible



# Project with the European Space Agency (ESA)

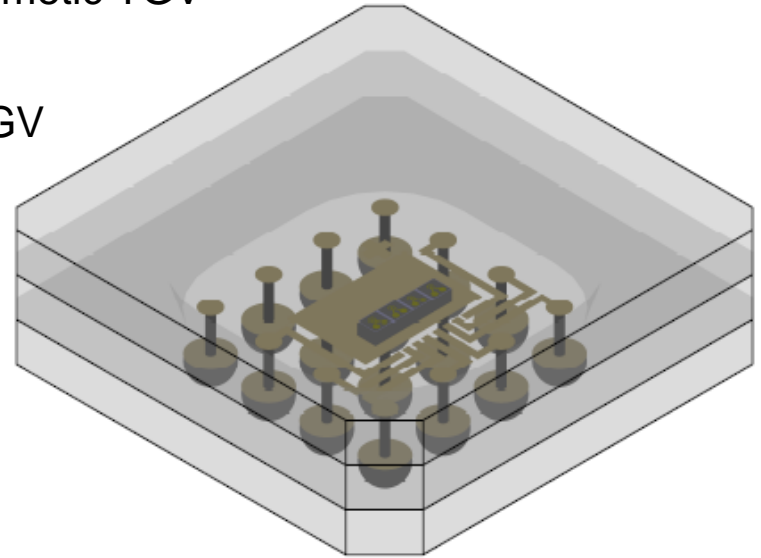
## Hermetic and Radiation Tolerant Glass Package for VCSELs

- Various glass materials available
- Package solution consists of hermetic Through-Glass-Vias (TGV) and a standard BGA balling
- Challenging the technique by using radiation hard glass, BK7G18



# Design result - all-in-glass rad hard package

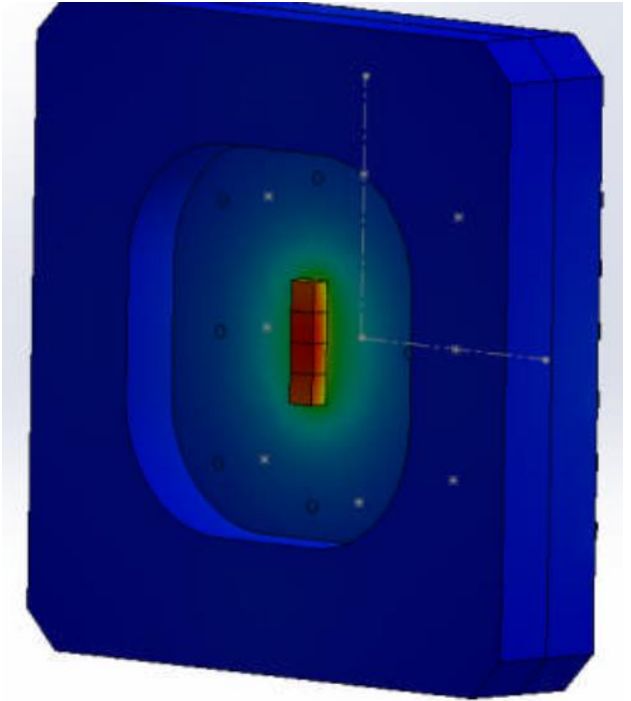
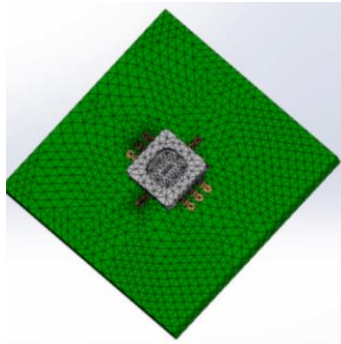
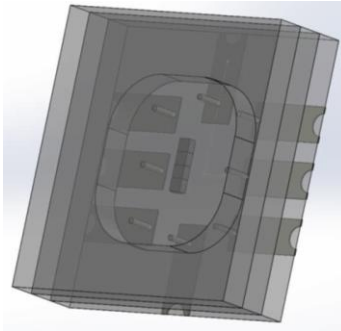
- Commercially available VCSEL, glass and hermetic TGV
- New glass and via material combination for TGV
- BK7G18 with FeNi42 vias
- Package size 1,5mm x 1,5mm x 0,5mm
- 3-layer structure, BGA



# Evaluating thermal performance – Thermal modelling

## Assumptions:

- Operating range 5...45°C
- Power dissipation 20mW for all devices
- No forced cooling
- Worst case scenario

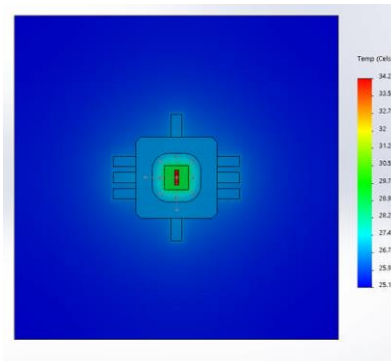
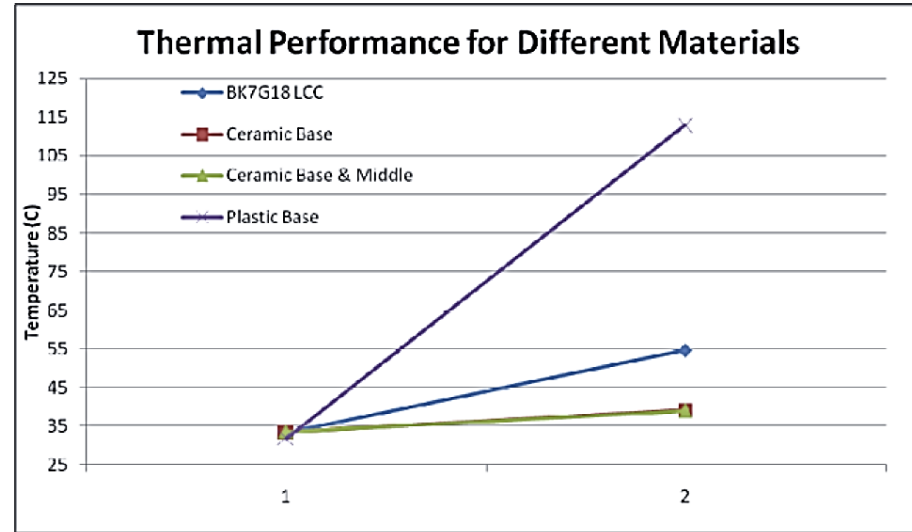




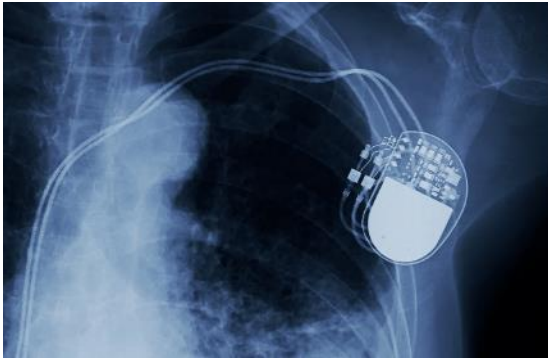
# Evaluating thermal performance - comparison to other materials

Thermal performance of the package can be easily further improved, for example by:

- Attaching the LGP to a PCB → 46°C
- Including metallized pad on both PCB and LGP → 43°C
- Higher dimension thermal TGV pad below the VCSEL

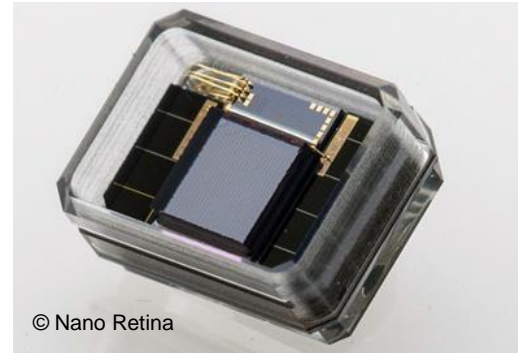


# Full-glass packages enable next generation active medical implants



## RF Transparency

- Wireless power and data transfer



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## Biocompatibility\*

- No additives or adhesives
- High hermeticity

"biocompatible according to ISO 10993-4 and 10993-5 (non-Hemolytic, non-Cytotoxic)



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## Room Temperature Process

- Flexible assembly sequence
- Die and wafer level possibility
- Suitable for many coatings and sensitive components

**Unmatched Miniaturization:** SCHOTT Primoceler™ all-glass packages come in sizes so small, you have to see it to believe it



# Questions?

Full visual inspection can be done with microscopes

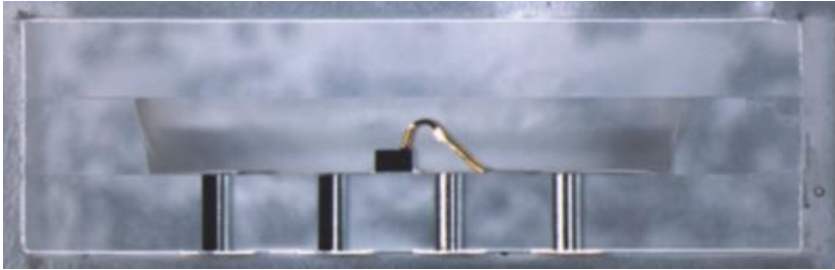
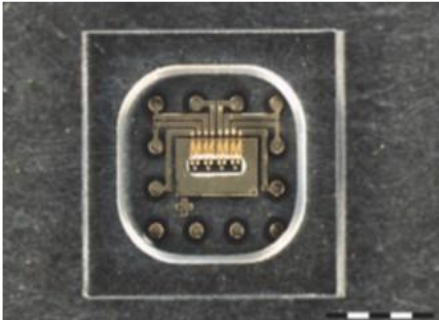


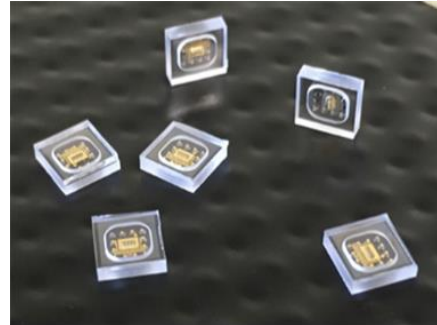
Figure: Cross-sectional image of the package.



Figure: Pre- and post-stress optical pictures.



Figures: Diced devices



# This presentation was presented at EPIC Meeting on New Space 2019

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